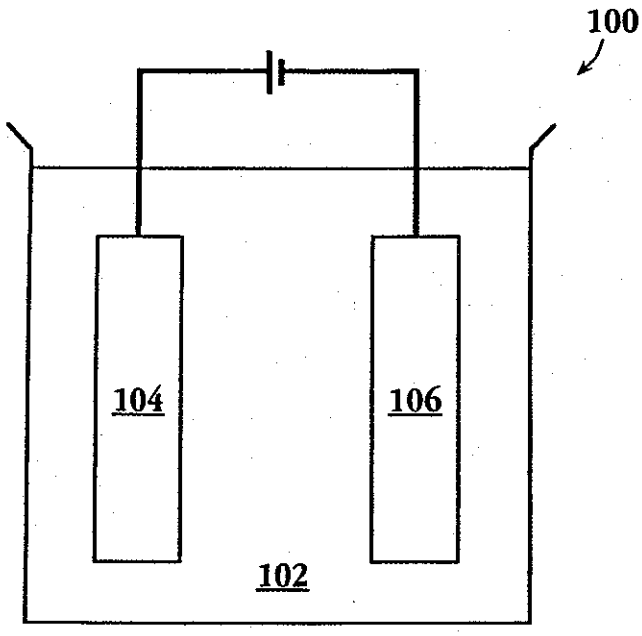


Fig. 1 *(prior art)*

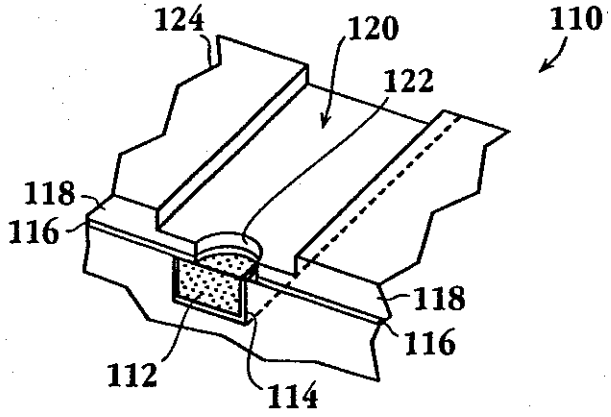


Fig. 2 *(prior art)*

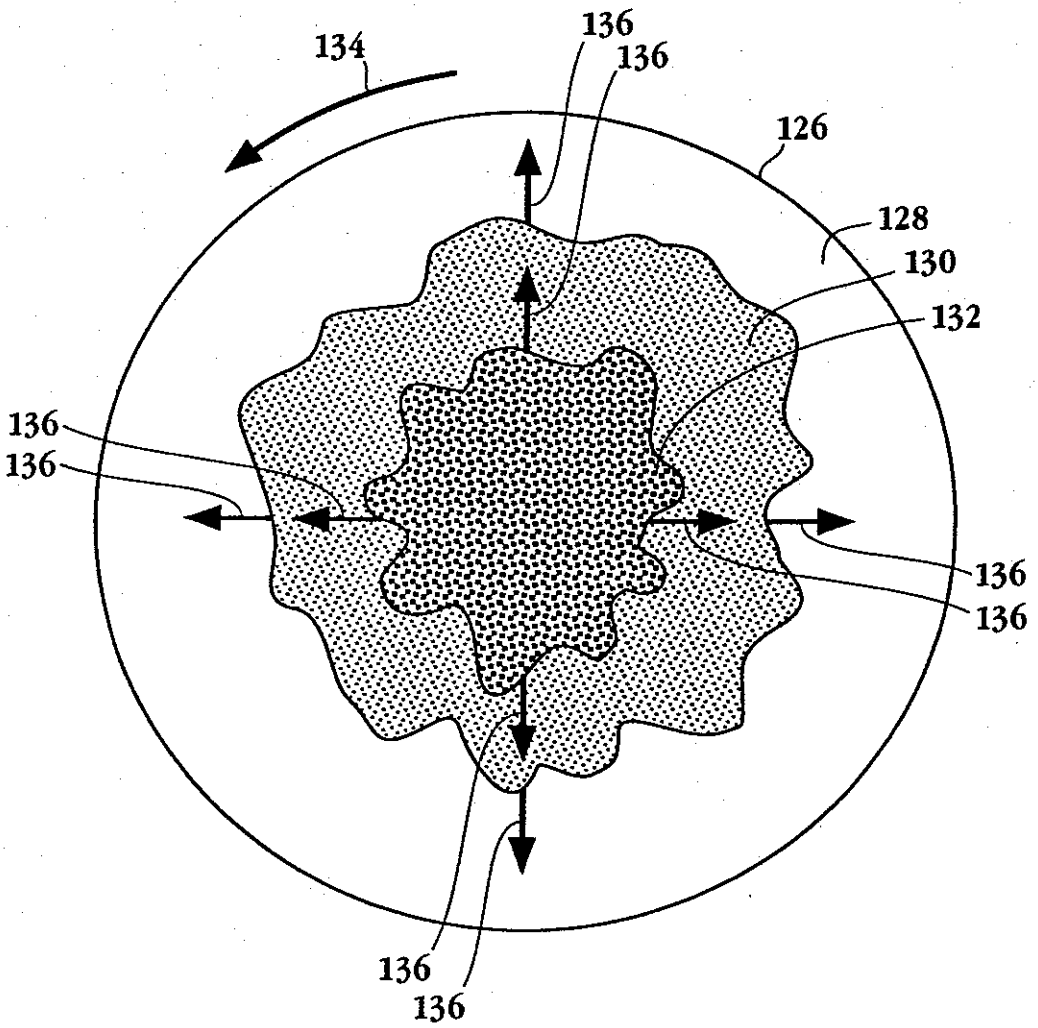


Fig. 3 *(prior art)*

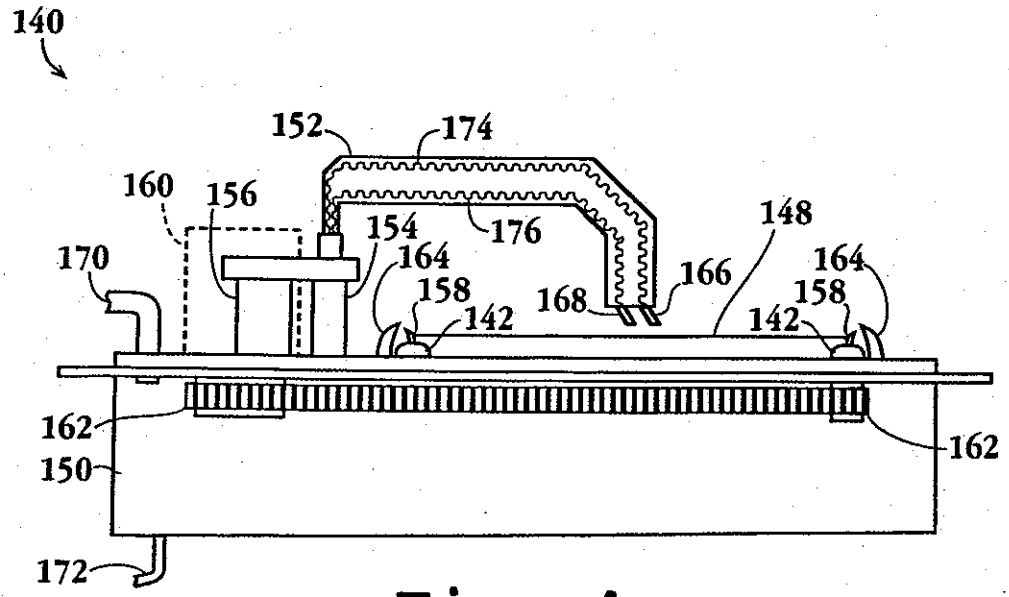

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Fig. 4

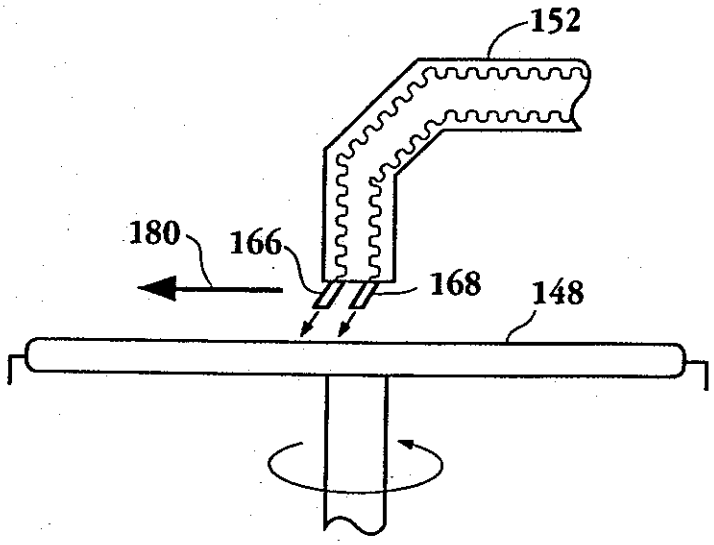


Fig. 5

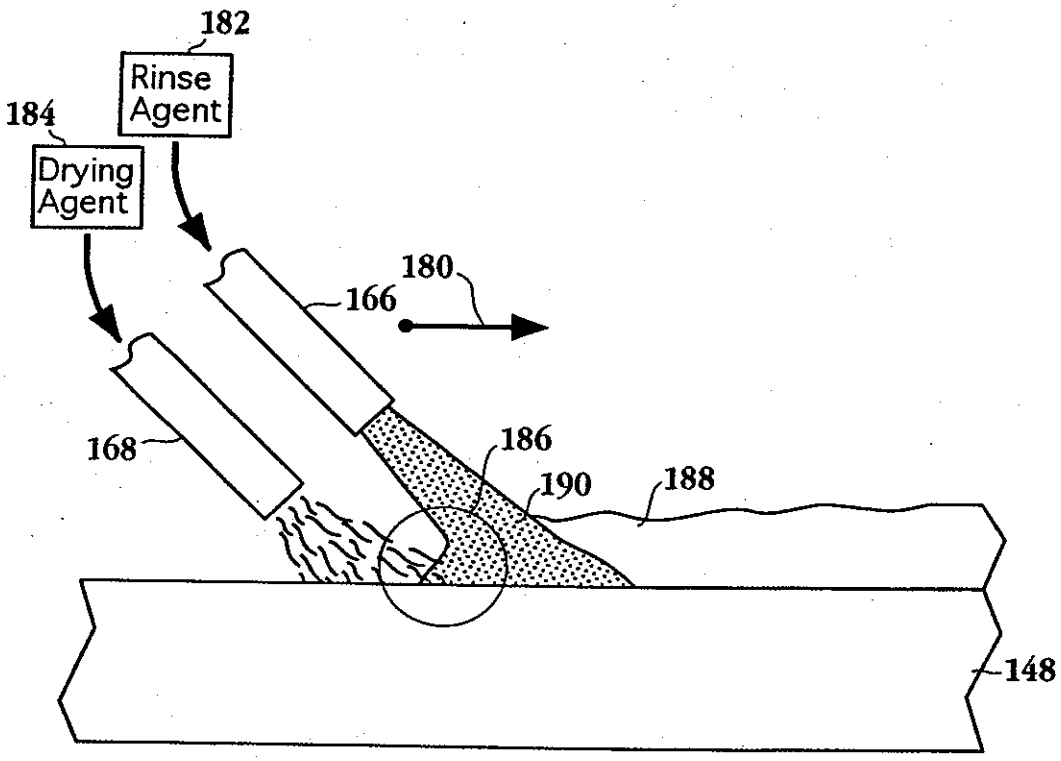


Fig. 6

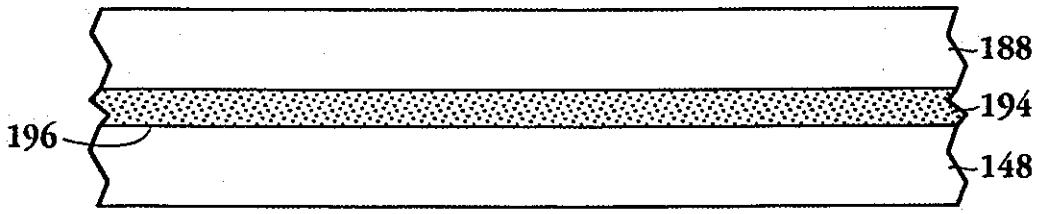


Fig. 7

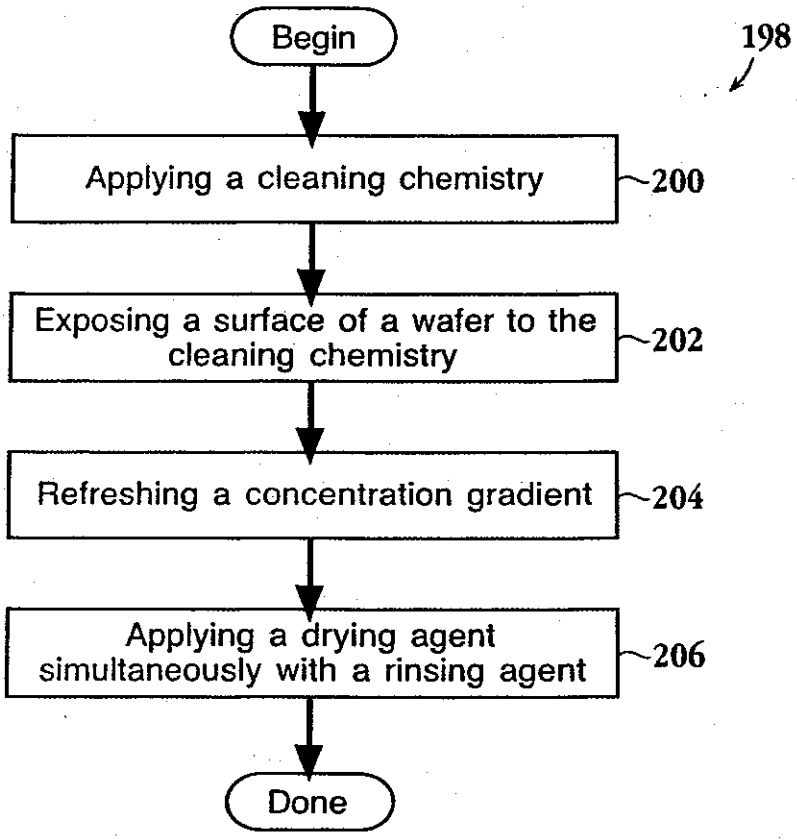

Begin
198
Applying a cleaning chemistry
200
Exposing a surface of a wafer to the cleaning chemistry
202
Refreshing a concentration gradient
204
Applying a drying agent simultaneously with a rinsing agent
206
Done

Fig. 8

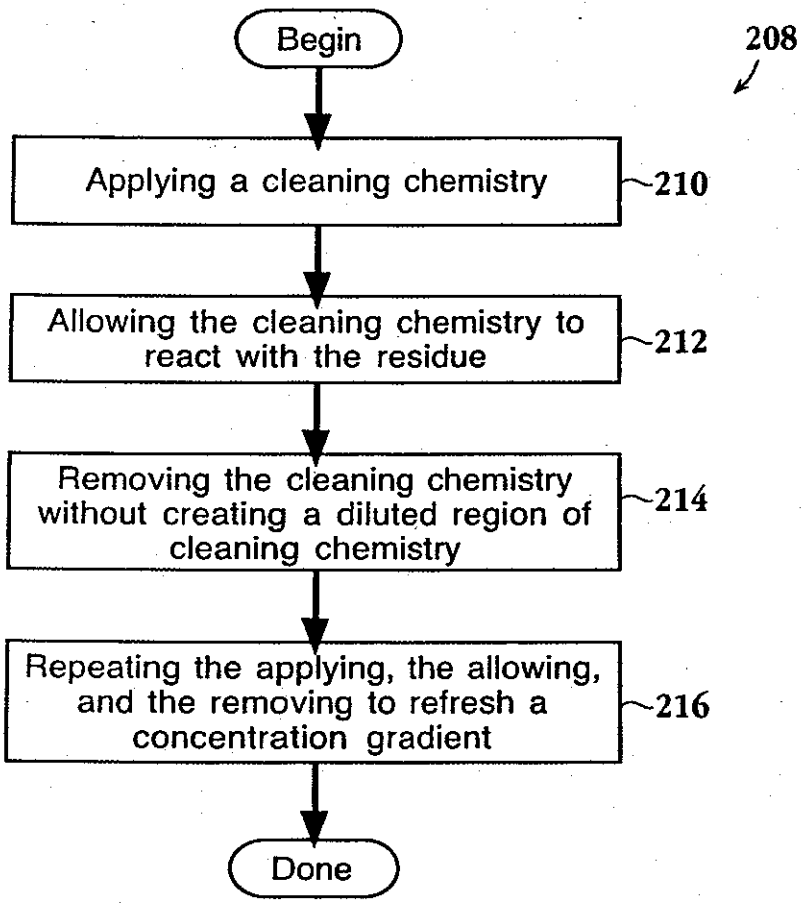

Begin
208
Applying a cleaning chemistry
210
Allowing the cleaning chemistry to react with the residue
212
Removing the cleaning chemistry without creating a diluted region of cleaning chemistry
214
Repeating the applying, the allowing, and the removing to refresh a concentration gradient
216
Done

Fig. 9